

# **Application Data Sheet**



## **Application Information**

Application number::	09802664
Filing Date::	03/09/01
Application Type::	Regular
Subject Matter::	Utility
Title::	Flip Chip Interconnection Structure
Attorney Docket Number::	CPAC 1003-1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	3
Small Entity?::	No

## **Applicant Information**

Applicant Authority Type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Rajendra
Middle Name::	D.
Family Name::	Pendse
City of Residence::	Fremont
State or Province of Residence::	CA
Country of Residence::	US
Street of mailing address::	5245 Diamond Common
City of mailing address::	Fremont
State or Province of mailing address::	CA
Country of mailing address::	US
Postal or Zip Code of mailing address::	94555

## Correspondence Information

Correspondence Customer Number:: 22470

## Representative Information

Representative Customer Number::	22470	
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## Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119(e)	60188570	03/10/2000

## Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::

## Assignee Information

Assignee name:: ChipPAC, Inc  
Street of mailing address:: 47400 Kato Road  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94538